



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-15
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS Group Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ABEO*F128BJ9	A	Z6RA	2015-07-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	7.5	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC125)	NAC	other		

Package Designator	Size	Nbr of instances	Shape	
WLB	2.66 x 2.56 x 0.5	34	bulk solder	
Comment	Package: WLCSP 2.66x2.56x0.5 34 PITCH 0.4 BALL 0.25; MDF valid for BLUENRG-MSCSP			

QueryList : ROHS directive 2011/65/EU _ANNEX IV	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ABE0*F128BJ9					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.197	mg	supplier	die	Silicon (Si)	7440-21-3		4.592	mg	883587	612267
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.011	mg	2117	1467
				supplier	metallisation	Copper (Cu)	7440-50-8		0.369	mg	71003	49200
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.031	mg	5965	4133
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.003	mg	577	400
				supplier	metallisation	Tungsten (W)	7440-33-7		0.001	mg	192	133
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.025	mg	4810	3333
				supplier	passivation	Silicon Oxide	7631-86-9		0.064	mg	12315	8533
				supplier	die polymer coat	4-Butyrolactone	96-48-0		0.091	mg	17510	12133
				supplier	die polymer coat	1-Methoxy-2-propyl acetate	108-65-6		0.010	mg	1924	1333
Back side coating		0.238	mg	supplier	resin	silica vitreous	60676-86-0		0.127	mg	533613	16933
				supplier	resin	Epoxy resin	Proprietary		0.048	mg	201681	6400
				supplier	resin	Acrylic polymer	Proprietary		0.048	mg	201681	6400
				supplier	resin	Bis-phenol A diglycidyl ether	25036-25-3		0.014	mg	58824	1867
				supplier	resin	carbon black	1333-86-4		0.001	mg	4202	133
				supplier	resin							
solder balls	Solder	2.038	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.003	mg	982826	267067
				supplier	solder alloy	Silver (Ag)	7440-22-4		0.024	mg	11776	3200
				supplier	solder alloy	Copper (Cu)	7440-50-8		0.010	mg	4907	1333
				supplier	solder alloy	Nickel (Ni)	7440-02-0		0.001	mg	491	133
				supplier	solder alloy							